

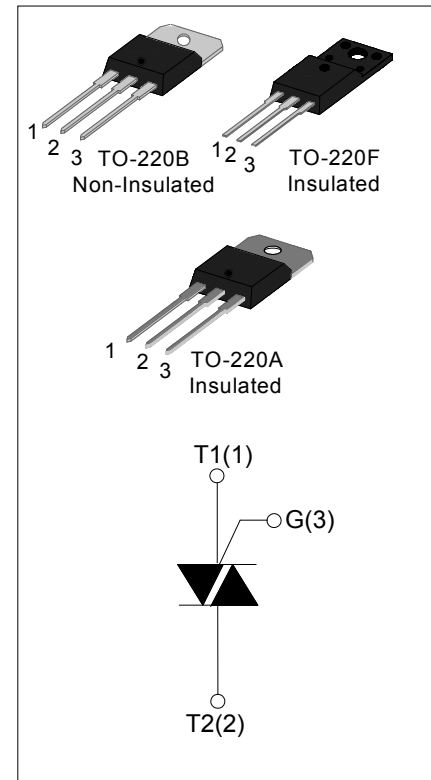
DESCRIPTION:

With high ability to withstand the shock loading of large current, YR BTA/BTB08 series triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.

From all three terminals to external heatsink, YR BTA/BTB08 provides a rated insulation voltage of 2500 Vrms, complying with UL standards .

MAIN FEATURES

Symbol	Value	Unit
$I_{T(RMS)}$	8	A
V_{DRM}/V_{RRM}	600 and 800 and 1200	V



ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Storage junction temperature range		T_{stg}	-40 - 150	°C
Operating junction temperature range		T_j	-40 - 125	°C
Repetitive peak off-state voltage ($T_j=25^\circ\text{C}$)		V_{DRM}	600/800/1200	V
Repetitive peak reverse voltage ($T_j=25^\circ\text{C}$)		V_{RRM}	600/800/1200	V
Non repetitive surge peak Off-state voltage		V_{DSM}	$V_{DRM} + 100$	V
Non repetitive peak reverse voltage		V_{RSM}	$V_{RRM} + 100$	V
RMS on-state current	TO-220B(Non-Ins) ($T_c=107^\circ\text{C}$)	$I_{T(RMS)}$	8	A
	TO-220A(Ins) ($T_c=100^\circ\text{C}$)			
	TO-220F(Ins) ($T_c=95^\circ\text{C}$)			

BTA/BTB08 TRIACs

Non repetitive surge peak on-state current (full cycle, F=50Hz)	I_{TSM}	80	A
I^2t value for fusing (tp=10ms)	I^2t	32	A ² s
Critical rate of rise of on-state current ($I_G=2 \times I_{GT}$)	dI/dt	50	A/ μ s
Peak gate current	I_{GM}	4	A
Average gate power dissipation	$P_{G(AV)}$	1	W
Peak gate power	P_{GM}	5	W

ELECTRICAL CHARACTERISTICS ($T_j=25^\circ\text{C}$ unless otherwise specified)

3 Quadrants

Symbol	Test Condition	Quadrant		Value				Unit
				TW	SW	CW	BW	
I_{GT}	$V_D=12V R_L=33\Omega$	I - II - III	MAX	5	10	35	50	mA
V_{GT}		I - II - III	MAX	1.5				V
V_{GD}	$V_D=V_{DRM} T_j=125^\circ\text{C}$ $R_L=3.3K\Omega$	I - II - III	MIN	0.2				V
I_L	$I_G=1.2I_{GT}$	I - III	MAX	20	25	50	70	mA
		II		25	35	70	90	
I_H	$I_{TM}=100\text{mA}$		MAX	15	20	40	60	mA
dV/dt	$V_D=2/3V_{DRM}$ Gate Open $T_j=125^\circ\text{C}$		MIN	50	200	500	1000	V/ μ s

4 Quadrants

Symbol	Test Condition	Quadrant		Value		Unit
				C	B	
I_{GT}	$V_D=12V R_L=33\Omega$	I - II - III	MAX	25	50	mA
		IV		50	70	
V_{GT}		ALL	MAX	1.5		V
V_{GD}	$V_D=V_{DRM} T_j=125^\circ\text{C}$ $R_L=3.3K\Omega$	ALL	MIN	0.2		V
I_L	$I_G=1.2I_{GT}$	I - III - IV	MAX	50	70	mA
		II		70	90	
I_H	$I_{TM}=200\text{mA}$		MAX	40	60	mA
dV/dt	$V_D=2/3V_{DRM}$ Gate Open $T_j=125^\circ\text{C}$		MIN	200	500	V/ μ s

STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
V_{TM}	$I_{TM} = 11A$ $t_p = 380\mu s$	$T_j = 25^\circ C$	1.5	V
I_{DRM}	$V_D = V_{DRM}$ $V_R = V_{RRM}$	$T_j = 25^\circ C$	5	μA
I_{RRM}		$T_j = 125^\circ C$	1	mA

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	junction to case(AC)	TO-220A(Ins)	2.9	$^\circ C/W$
		TO-220B(Non-Ins)	1.9	
		TO-220F(Ins)	2.9	

FIG.1: Maximum power dissipation versus RMS on-state current

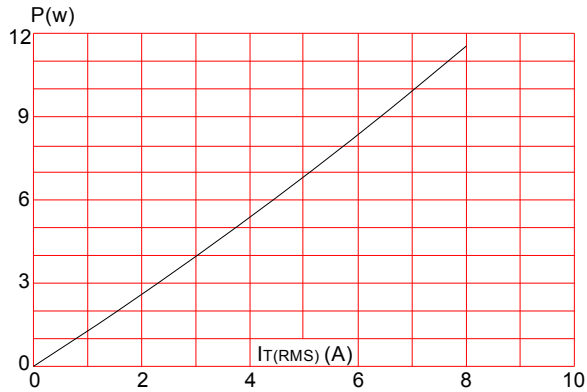


FIG.2: RMS on-state current versus case temperature

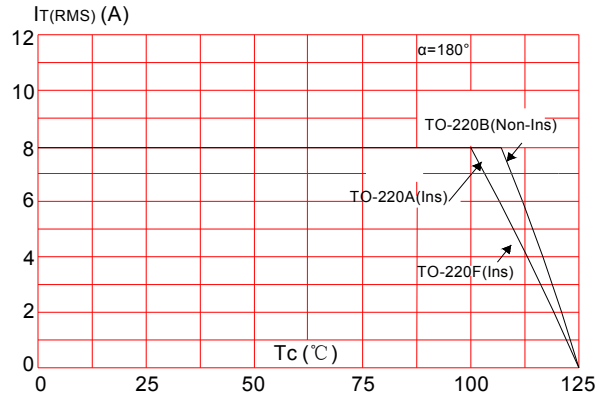


FIG.3: Surge peak on-state current versus number of cycles

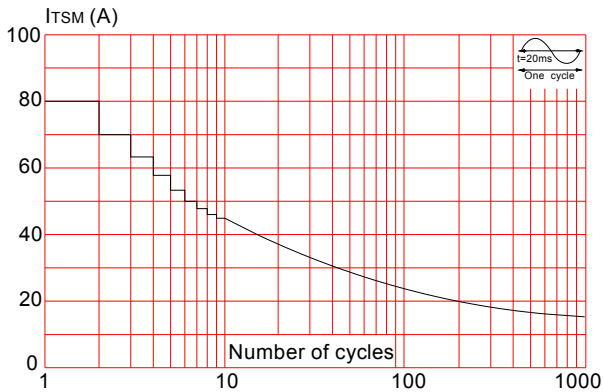


FIG.4: On-state characteristics (maximum values)

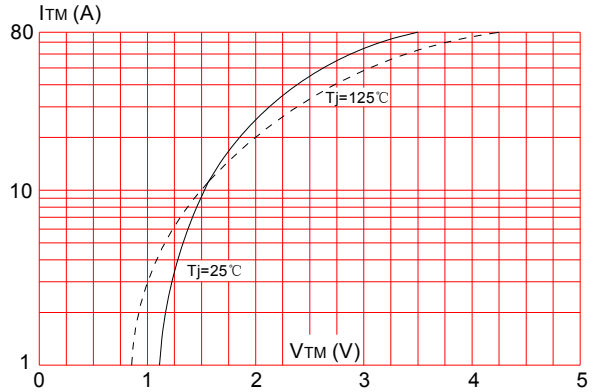


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 20\text{ms}$, and corresponding value of I^2t ($di/dt < 50\text{A}/\mu\text{s}$)

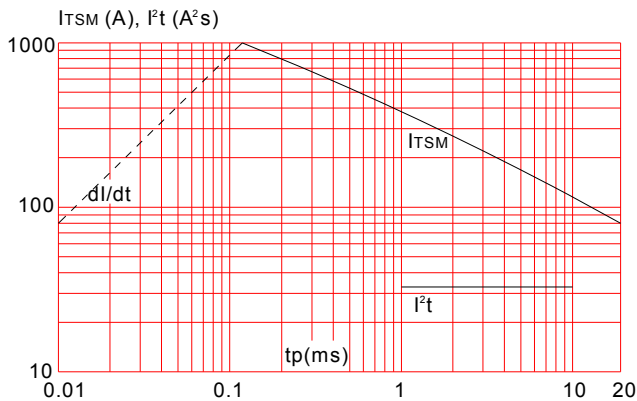


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature

